Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTION:**

1. **ANODE**
2. **CATHODE**

**.035”**

**1 2**

**MIC4040B**

**MASK**

**REF**

**.034”**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size = .004 x .004”**

**Backside Potential: FLOAT**

**Mask Ref: MIC4040B**

**APPROVED BY: DK DIE SIZE .034” X .035” DATE: 7/7/22**

**MFG: MICREL/MICROCHIP THICKNESS .020” P/N: LM4040B1-2.5**

**DG 10.1.2**

#### Rev B, 7/1